

### Description

The ICE27C512 is a low-power, high-performance 512k(524288) bit one-time programmable read only memory (OTP EPROM) organized as 64K by 8 bits. It is single 5V power supply in normal read mode operation. Any byte can be accessed in less than 70ns. The ICE27C512 typically consumes 10mA, standby mode supply current typically less than 10μA. Two lines control ( $\overline{CE}$ ,  $\overline{OE}$ ) to give designers the flexibility to prevent bus contention. Programming time is typically only 100 μs/byte. The Integrated Product Identification Code electronically identifies the device and manufacturer. This feature is used by industry standard programming equipment to select the proper programming algorithms and voltages.

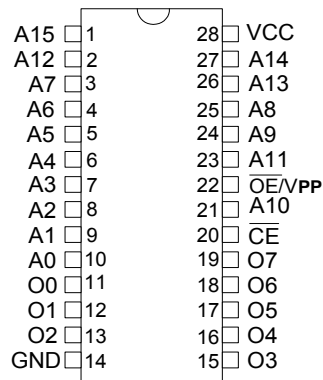
### Features

- Fast Read Access Time : 70ns
- Low-Power consumption
  - 1 μA Typ. Standby
  - 10 mA max. Active at 5MHz
- JEDEC Standard Packages
  - 28-Lead 600-mil PDIP
  - 32-Lead PLCC
  - 28-Lead TSOP
- Operating voltage : 5V ±10%
- High Reliability CMOS Technology
  - 2000V ESD Protection
  - 200 mA Latchup Immunity
- Programming time : 100 μs/byte (typical)
- CMOS and TTL Compatible Inputs and Outputs
- Integrated Product Identification Code

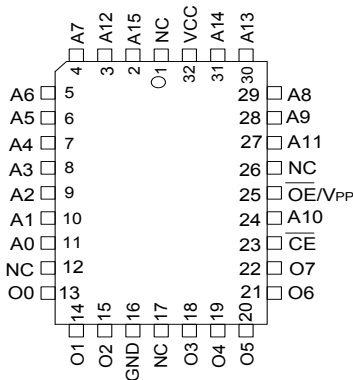
### Pin Configurations

Pin Name	Function
A0 – A15	Addresses
O0 – O7	Outputs
$\overline{CE}$	Chip Enable
$\overline{OE}/V_{PP}$	Output Enable
NC	No Connect

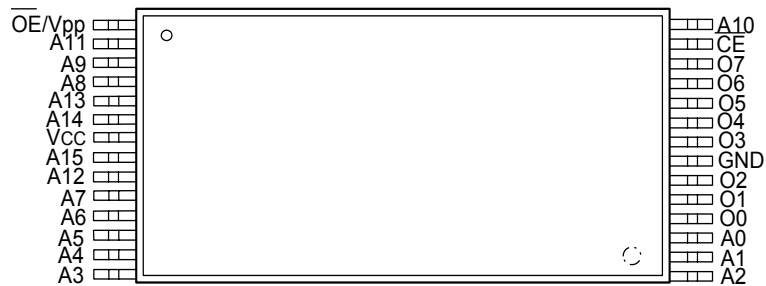
### PDIP, SOP, SOLT Top View



### PLCC Top View

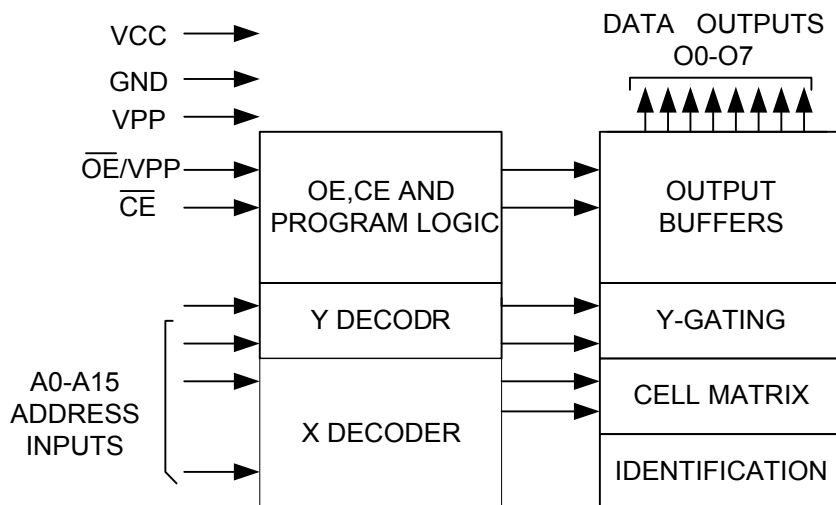


### TSOP Top View



Pin Assignment of 28-Pin TSOP

**Block Diagram**



**Absolute Maximum Rating**

Operation Temperature Commercial .....	0 to +70
Storage Temperature .....	-65 to +125
Voltage on Any Pin with Respect to Ground .....	-0.6V to +7.0V <sup>(1)</sup>
Vpp Supply Voltage with Respect to Ground.....	-0.6V to +13.5V <sup>(1)</sup>

**Operating Modes**

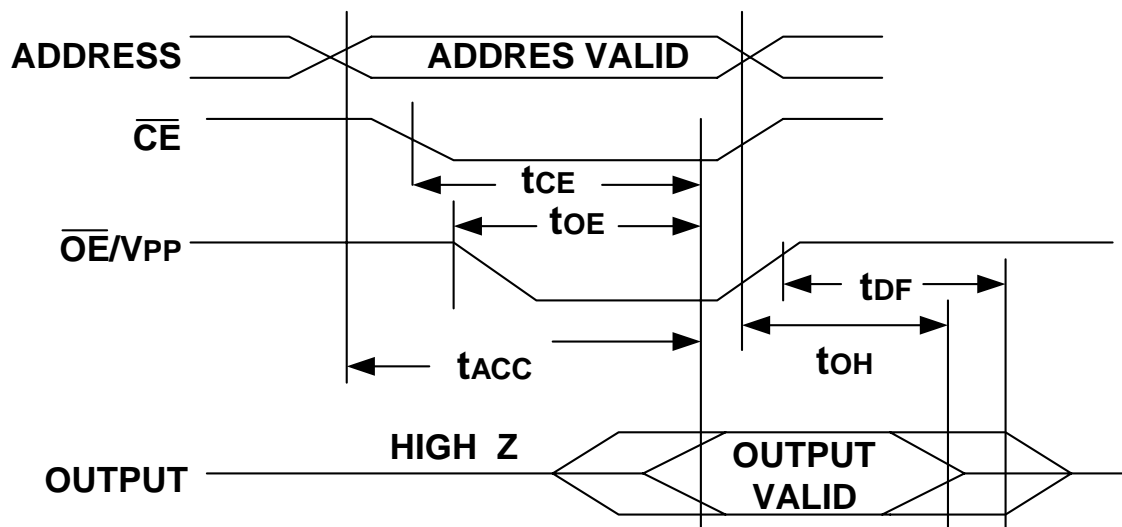
Mode\Pin	$\overline{CE}$	$\overline{OE}/MPP$	Ai	Outputs
Read	$V_{IL}$	$V_{IL}$	Ai	D <sub>OUT</sub>
Output Disable	X	$V_{IH}$	X	High Z
Standby	$V_{IH}$	X	X	High Z
Rapid Program <sup>(2)</sup>	$V_{IL}$	$V_{PP}$	Ai	D <sub>IN</sub>
PGM Inhibit	$V_{IH}$	X	X	High Z
Product Identification <sup>(4)</sup>	$V_{IL}$	$V_{IL}$	A9 = $V_H$ <sup>(3)</sup> A0,A1 = $V_{IH}$ or $V_{IL}$ A2 – A15 = $V_{IL}$	Identification Code

- Notes: 1. X can be  $V_{IL}$  or  $V_{IH}$ .  
 2. Refer to Programming Characteristics.  
 3.  $V_H = 12 \pm 0.5V$ .  
 4. See Product Identification Code item.

## DC and Operating Characteristics for Read Operation

Symbol	Parameter	Condition		Min	Max	Units
$I_{LI}$	Input Load Current	$V_{IN} = 0V$ to $V_{CC}$	Com.		$\pm 1$	$\mu A$
$I_{LO}$	Output Leakage Current	$V_{OUT} = 0V$ to $V_{CC}$	Com.		$\pm 5$	$\mu A$
$I_{SB}$	$V_{CC}^{(1)}$ Standby Current	$I_{SB1}(\text{CMOS}), \overline{CE} = V_{CC} \pm 0.3V$			3	$\mu A$
		$I_{SB2}(\text{TTL}), \overline{CE} = 2.0$ to $V_{CC} + 0.5V$			500	$\mu A$
$I_{CC}$	$V_{CC}$ Active Current	$f = 5\text{MHz}, I_{OUT} = 0\text{mA}, \overline{CE} = V_{IL}$			10	mA
$V_{IL}$	Input Low Voltage			-0.6	0.8	V
$V_{IH}$	Input High Voltage			2.0	$V_{CC} + 0.5$	V
$V_{OL}$	Output Low Voltage	$I_{OL} = 2.1 \text{ mA}$			0.4	V
$V_{OH}$	Output High Voltage	$I_{OH} = -400 \mu A$		2.4		V

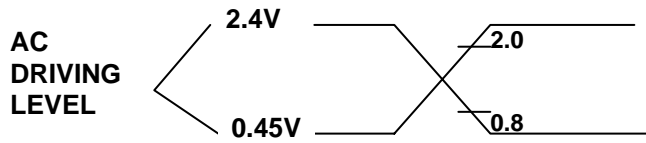
Notes: 1.  $V_{CC}$  must be applied simultaneously or before  $V_{PP}$  and removed simultaneously or after  $V_{PP}$ .  
 2.  $V_{PP}$  may be connected directly to  $V_{CC}$  except during programming. The supply current would then be the sum of  $I_{CC}$  and  $I_{PP}$ .

AC Waveforms for Read Operation <sup>(1)</sup>

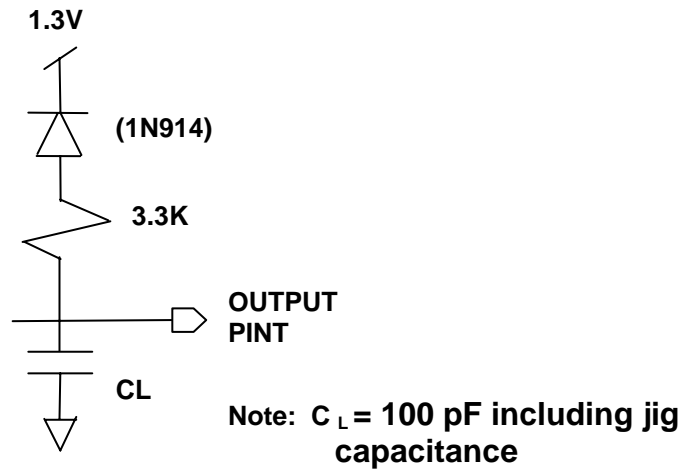
Notes:

- $\overline{OE}/V_{PP}$  may be delayed up to  $t_{CE} - t_{OE}$  after the falling edge of  $\overline{CE}$  without impact on  $t_{CE}$ .
- $\overline{OE}/V_{PP}$  may be delayed up to  $t_{ACC} - t_{OE}$  after the address is valid without impact on  $t_{ACC}$ .
- This parameter is only sampled and is not 100% tested.
- Output float is defined as the point when data is no longer driven.

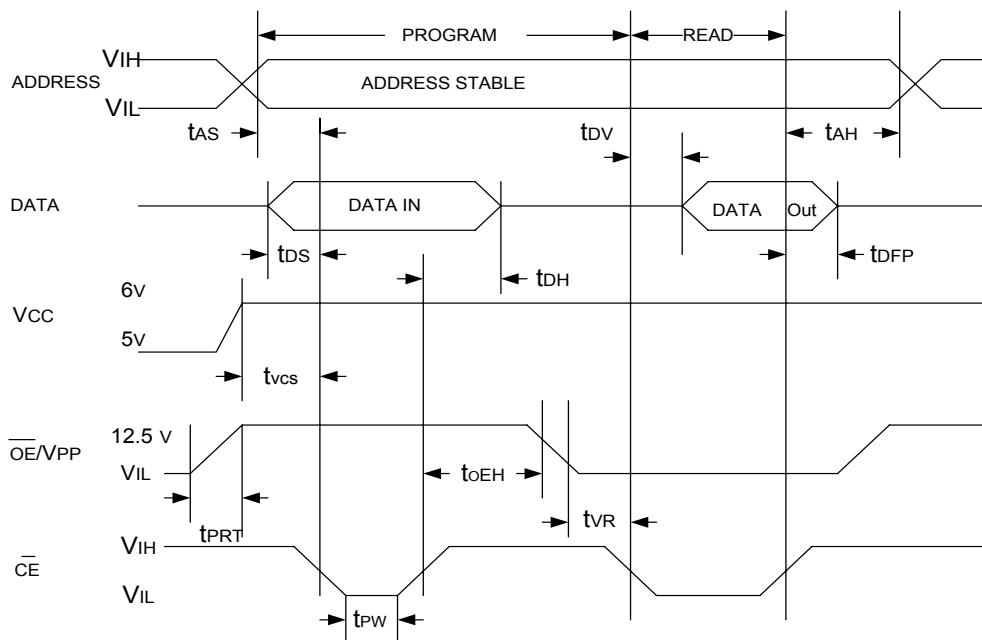
**Input Test Waveforms and Measurement Levels**



**Output Test Load**



**Programming Waveforms**



**Notes:**

1. The Input Timing Reference is 0.8V for  $V_{IL}$  and 2.0V  $V_{IH}$ .
2.  $t_{OE}$  and  $t_{DFP}$  are characteristics of the device but must be accommodated by the programmer.
3. When programming the ICE27C512 at 0.1 $\mu$  F capacitor is required across  $V_{pp}$  and ground to suppress spurious voltage transients.

**DC Programming Characteristics**
 $T_A = 25 \pm 5$  ,  $V_{CC} = 5.5 \pm 0.5V$ ,  $V_{PP} = 12 \pm 0.5V$ 

Symbol	Parameter	Test Conditions	Limits		Units
			Min	Max	
$I_{LI}$	Input Load Current	$I_{IN} = V_{IL}, V_{IH}$		$\pm 10$	$\mu A$
$V_{IL}$	Input Low Level		-0.6	0.8	V
$V_{IH}$	Input High Level		2.0	$V_{CC} + 1$	V
$V_{OL}$	Output Low Voltage	$I_{OL} = 2.1 \text{ mA}$		0.4	V
$V_{OH}$	Output High Voltage	$I_{OH} = -400 \mu A$	2.4		V
$I_{CC2}$	Vcc Supply Current (Program and Verify)			40	mA
$I_{PP2}$	$\overline{OE}$ NPP Current	$\overline{CE} = V_{IL}$		20	mA
$V_{ID}$	A9 Product Identification Voltage		11.0	12.5	V

**AC Characteristics for Read Operation**

Symbol	Parameter	condition	ICE27C512		Units
			-70		
			Min	Max	
$t_{ACC}^{(3)}$	Address to Output Delay	$\overline{CE} = \overline{OE}$ NPP= $V_{IL}$		70	ns
$t_{CE}^{(2)}$	$\overline{CE}$ to Output Delay	$\overline{OE}$ NPP= $V_{IL}$		70	ns
$t_{OE}^{(2)(3)}$	$\overline{OE}$ Npp to Output Delay	$\overline{CE} = V_{IL}$		30	ns
$t_{DF}^{(4)(5)}$	$\overline{OE}$ NPP or $\overline{CE}$ Hight to Output Float, whichever occurred first			25	ns
$t_{OH}$	Output Hold from Address, $\overline{CE}$ or $\overline{OE}$ NPP whichever occurred first		7		ns

Notes:2,3,4,5.-see AC Waveforms for Read Operation.

**AC Programming Characteristics**
 $T_A = 25 \pm 5$  ,  $V_{CC} = 5.5 \pm 0.5V$ ,  $V_{PP} = 12.0 \pm 0.5V$ 

Symbol	Parameter	Test Conditions	Limits		Units
			Min	Max	
$t_{AS}$	Address Setup Time	Input Rise and Fall Times (10% to 90%) 20ns	2		$\mu S$
$t_{OE\overline{H}}$	$\overline{OE} N_{pp}$ Hold Time		2		$\mu S$
$t_{OES}$	$\overline{OE} N_{pp}$ Setup Time		2		$\mu S$
$t_{DS}$	Data Setup Time		2		$\mu S$
$t_{AH}$	Address Hold Time		0		$\mu S$
$t_{DH}$	Data Hold Time	Input Pulse Levels 0.45V to 2.4V	2		$\mu S$
$t_{DFP}$	$\overline{OE} N_{pp}$ High to Output Float Delay <sup>(2)</sup>		0	130	ns
$t_{VCS}$	Vcc Setup Time	Input Timing Reference Level 0.8V to 2.0V	2		$\mu S$
$t_{PW}$	$\overline{CE}$ Program Pulse Width <sup>(3)</sup>		95	105	$\mu S$
$t_{DV}$	Data Valid from $\overline{CE}$	Output Timing Reference Level 0.8V to 2.0V		150	ns
$t_{PRT}$	Vpp Pulse Rise Time During Programming		50		ns
$t_{VR}$	$\overline{OE} N_{PP}$ Recover time		2		$\mu S$

Notes: 1. Vcc must be applied simultaneously or before  $\overline{OE} N_{PP}$  and removed simultaneously or after  $\overline{OE} N_{PP}$

2. This parameter is only sampled and is not 100% tested. Output Float is defined as the point where data is no longer driven – see timing diagram.

3. Program Pulse width tolerance is 100  $\mu sec \pm 5\%$ .

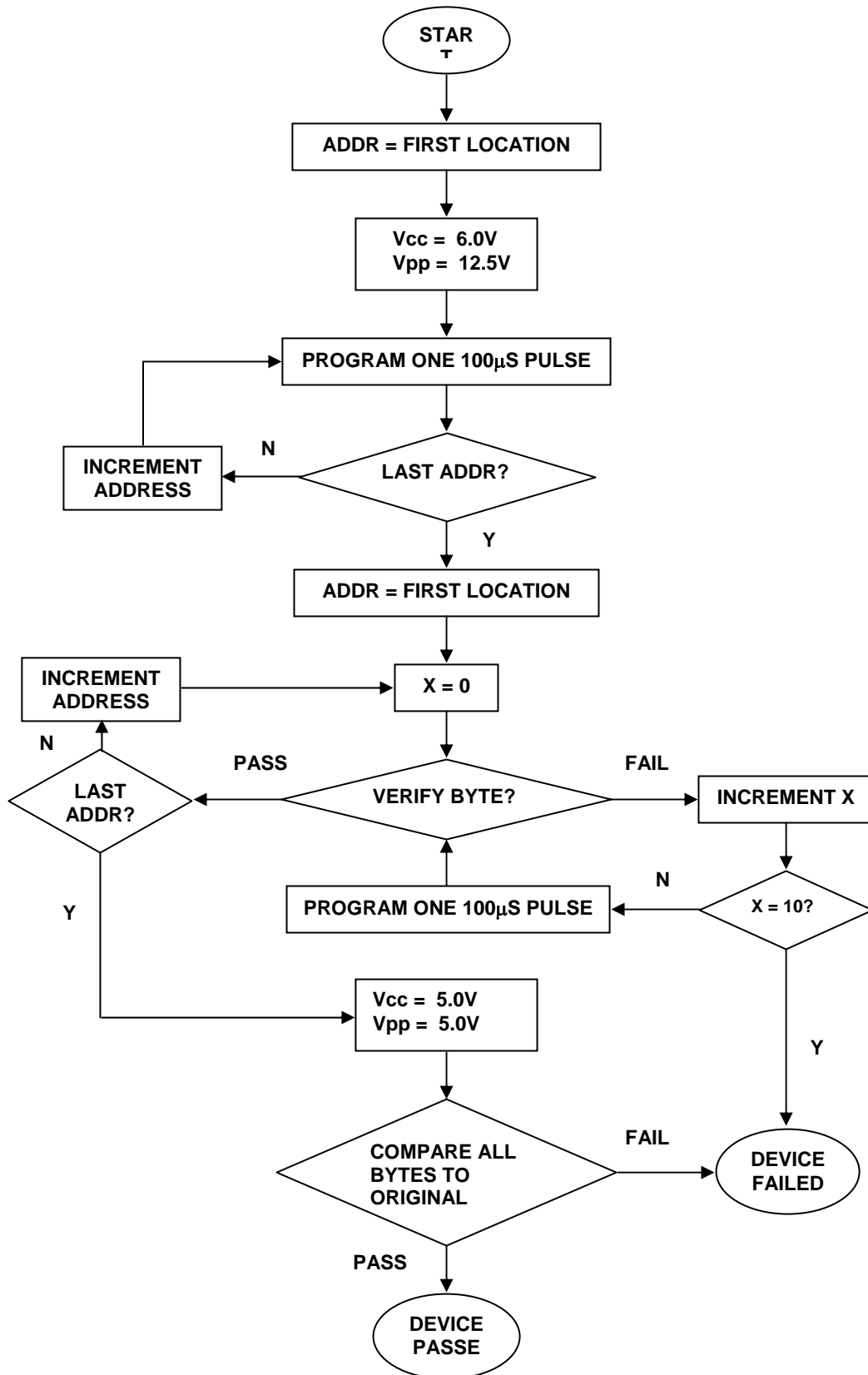
**Product Identification Code**

Codes	Pins										Hex Data
	A1	A0	O7	O6	O5	O4	O3	O2	O1	O0	
Continue Code 1	0	0	0	1	1	1	1	1	1	1	7F
Continue Code 2	0	1	0	1	1	1	1	1	1	1	7F
Manufacturer	1	0	0	1	0	1	1	1	1	0	5E
Device Type	1	1	1	1	0	0	0	0	0	0	C0

**Rapid Programming Algorithm**

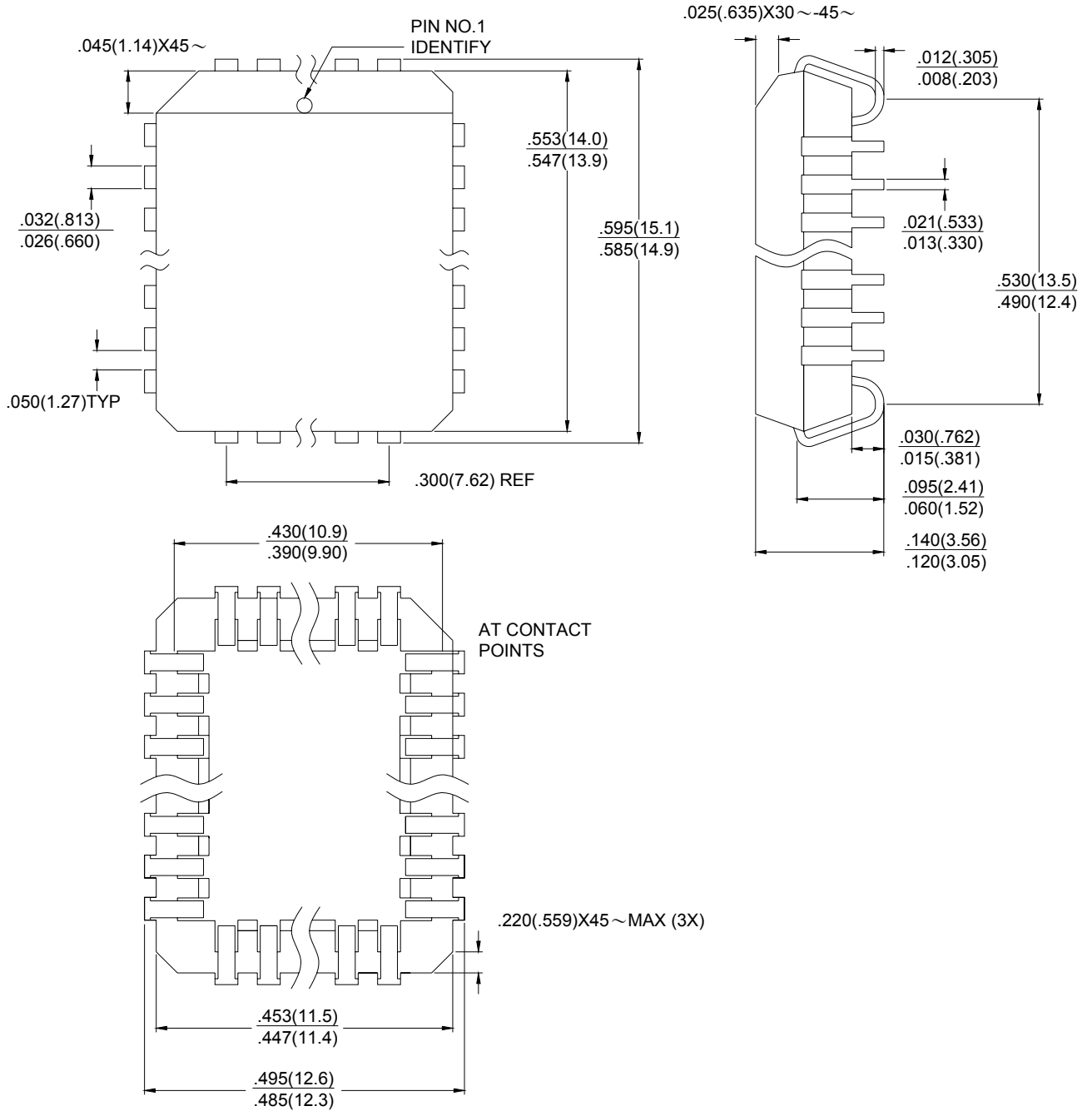
A 100  $\mu s$   $\overline{CE}$  pulse width is used to program. The address is set to the first location. Vcc is raised to 6.0V and  $\overline{OE} N_{PP}$  is raised to 12.5V. Each address is first programmed with one 100 $\mu s$   $\overline{CE}$  pulse without verification. Then a verification reprogramming loop is executed for each address. In the event a byte fails to pass verification, up to 10 successive 100  $\mu s$  pulses are applied with a verification after each pulse. If the byte fails to verify after 10 pulses have been applied, the part is considered failed. After the byte verifies properly, the next address is selected until all have been checked. All bytes are read again and compared with the original data to determine if the device passes or fails.

## Fast Programming Flowchart



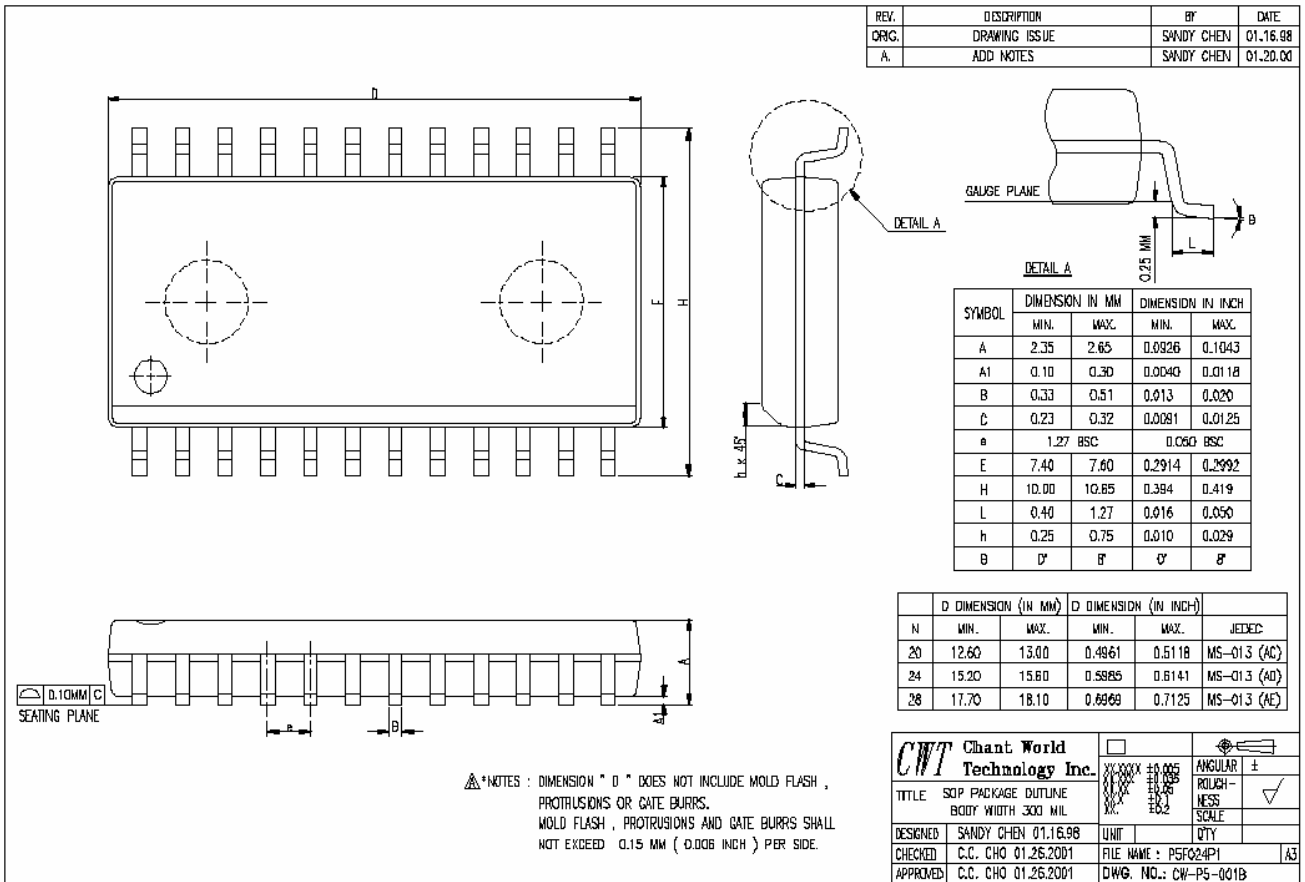
Packaging Information

32P, 32-Lead, Plastic J-Leaded Chip Carrier (PLCC)  
 Dimensions in Inches and (Millimeters)  
 JEDEC STANDARD MS-016 AE

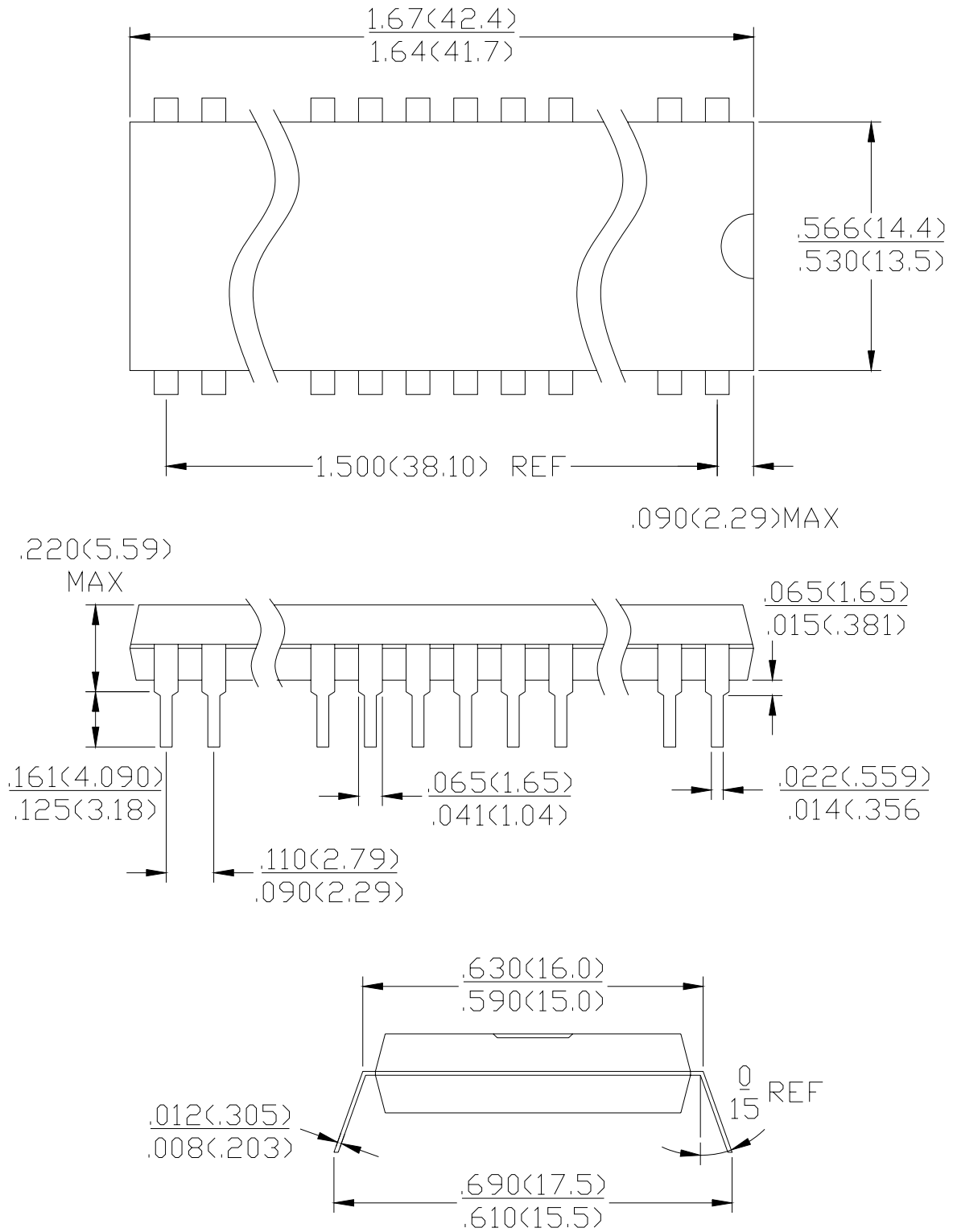




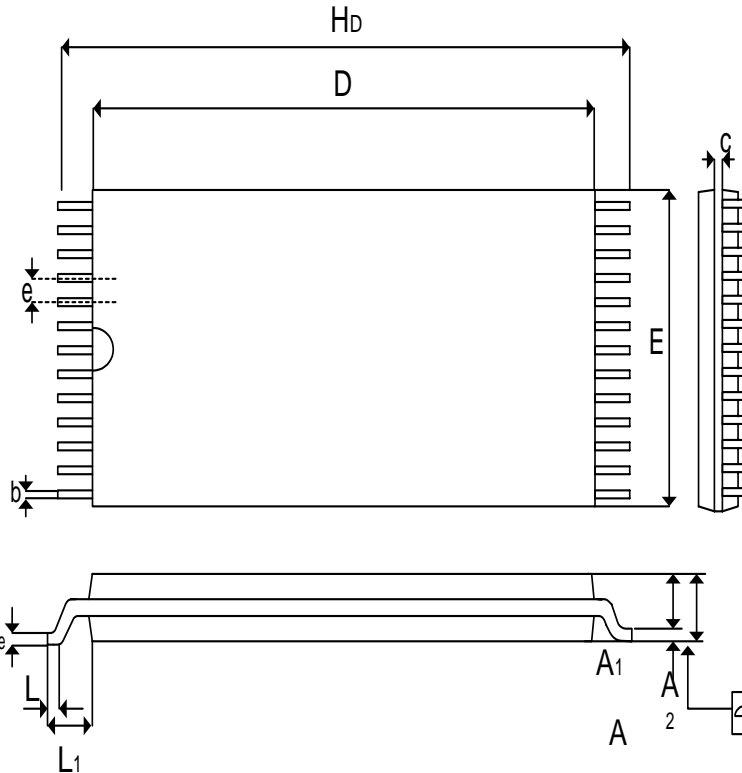
## 28Pin, 28-Lead, Small Outline Package (SOP) Dimensions in Inches and (Millimeters)



28Pin, 28-Lead, 0.600" wide, Plastic Dual Inline Package (PDIP)  
 Dimensions in Inches and (Millimeters)



28Pin, 28-Lead, Plastic Thin Small Outline Package (TSOP)  
 Dimensions in Millimeters and (Inches)\*  
 JEDEC OUTLINE MO- 141 BD



Symbol	Dimension in Inches			Dimension in mm		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	-	-	0.047	-	-	1.20
A <sub>1</sub>	0.002	-	0.006	0.05	-	0.15
A <sub>2</sub>	0.035	0.040	0.041	0.95	1.00	1.05
b	0.007	0.008	0.011	0.17	0.20	0.27
c	0.004	0.006	0.008	0.10	0.15	0.21
D	0.461	0.465	0.469	11.70	11.80	11.90
E	0.311	0.315	0.319	7.90	8.00	8.10
H <sub>D</sub>	0.520	0.528	0.536	13.20	13.40	13.60
e	-	0.022	-	-	0.55	-
L	0.020	0.024	0.028	0.50	0.60	0.70
L <sub>1</sub>	-	0.010	-	-	0.25	-
Y	0.000	-	0.004	0.00	-	0.10
	0	3	5	0	3	5

Note: Controlling dimension: Millimeters

**PRODUCTION ORDERING INFORMATION**

**Example**

ICE27C512 - XX XX

